Title: METHOD FOR FORMING AN INTEGRATED CIRCUIT INTERCONNECT USING A DUAL POLY PROCESS

## IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning at page 1, after the title is amended as follows:

This application is a Continuation of U.S. Application No. 09/351,884, filed July 13, 1999, now abandoned, which is a Continuation of Application No. 08/390,714, filed February 17, 1995, now U.S. Patent No. 6,740,573, which applications are incorporated herein by reference.